

**AMENDMENTS TO THE SPECIFICATION**

***In the Specification:***

Please **AMEND** the specification as shown in the following marked up line, which shows changes made relative to the immediate prior version.

Please **AMEND** the paragraph beginning on page 4, line 16 (and ending at page 6, line 1) as follows:

Although various methods such as laser welding and spot welding are taken for welding the mask to the frame, a welding flash having a height of several  $\mu\text{ms}$  to several hundreds of  $\mu\text{ms}$  is generated on a mask surface which is contacted to the substrate during welding. As shown in FIG. 4(a), a typical deposition method is performed by rotating the substrate with an evaporation source 48 displaced from a center position of the substrate 50. However, when the deposition is performed with this welding flash remained as it is, the welding flash 43 protrudes at a welding portion between the frame 41 and the mask 42 as shown in FIG. 4(b), so that a gap 44 is created between the substrate 45 and the mask 42. For example, when a luminescent layer 47 is deposited from one evaporation source 48 as shown in the same Figure, a deposition incidence angle at the farthest end of the deposition area from the evaporation source ~~46-48~~ and a deposition incidence angle at the nearest end of the deposition area from the evaporation source ~~46-48~~ become different. The deposition incidence angle at the farthest end of the deposition area is minimized (~~53~~), and at the farthest side from the center of the substrate, the deposition is performed in a larger area than a predetermined area (the same width as that of ITO). Further, it

is necessary to allow a uniform part of the luminescent layer to correspond to the ITO electrode, but the uniform part may not correspond to the ITO electrode because a center of the uniform part of the luminescent layer which is formed at the nearest position from the evaporation source (deposition incidence angle is maximum (52)) and a center of the ITO electrode are displaced from each other due to the fact that the position which is closer to the center of the substrate is shaded with a slit. Further, when the luminescent layer is required to be coated for every each color in order to achieve full-colorization, the layer is formed with the same mask displaced by a pitch of ITO. However, at the end of the deposition area, the layer is deposited onto an adjacent pixel portion (an adjacent ITO electrode 46) at the farthest position from the center of the substrate. In particular, this tendency becomes significant as the pitch and space become narrower.